

Form No.: QF-1274

Edition: 2

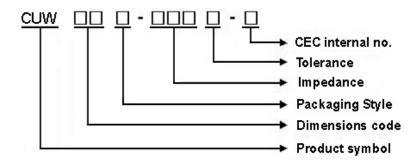
ISO9001 & ISO14001 & TS16949 CHILISIN ELECTRONICS CORP.

RoHS & Halogen Free & REACH Compliance.

SPECIFICATION FOR APPROVAL

Customer :	研華		
Customer P/N:			
Drawing No:			
Quantity:	0 Pcs. Date:	2016/06/20	
Chilisin P/N:	CUW11T-90	00M-N	
	SPECIFICATION ACCEPTED BY:		
COMPONENT ENGINEER			
ELECTRICAL ENGINEER			
MECHANICAL ENGINEER			
APPROVED			
REJECTED			
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Chilisin Electronics (Henan) Co	Postal Code:454350 Suzhou,China TEL:+86-391-717-0682 Postal Code:215129 TEL:+86-512-6841-2350		
Drawn by 林帛穎 audrey.lin	Checked by 溫美玲 ling	Approved by 陳瑞揚 ryan.chen	

- 1 Scope: This specification applies to CUW FILTER
- 2 Part Numbering:



3 Rating:

Operating Temperature: $-4.0 \,^{\circ}\text{C} \sim 1.0.5 \,^{\circ}\text{C}$ (Including self - temperature rise)

Storage Temperature: $2~0~{}^{\circ}{\rm C} \sim 2~5~{}^{\circ}{\rm C}$ R.H. 6~5~%(In Tape & Reel Condition)

4 Marking:

No Marking

5 Standard Testing Condition

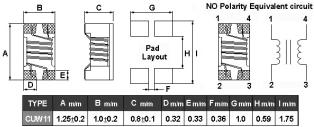
	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°C)	20 to 30°C
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH



ISO9001 & ISO14001 & TS16949 CHILISIN ELECTRONICS CORP.

CUW11T Series Specification

6 Configuration and Dimensions:



7 Electrical Characteristics:

Part No.	Z (Ω)	RDC (Ω)Max.	IDC (mA)	Rated Voltage (Vdc)	Insulation Resistance (MΩ)(min)	Tolerance (±%)	Test Freq. (MHz)
CUW11T-250□-N	25	0.3	400	20	10	30	100
CUW11T-600□-N	60	0.4	300	20	10	20	100
CUW11T-670□-N	67	0.25	300	50	10	20	100
CUW11T-900□-N	90	0.3	250	50	10	20	100
CUW11T-121 □-N	120	0.4	200	50	10	20	100
CUW11T-161 □-N	160	0.43	160	50	10	20	100
CUW11T-201□-N	200	0.8	120	50	10	20	100
CUW11T-331□-N	330	1.3	100	50	10	25	100

NOTE: □-tolerance M=±20% / Y=±25% / T=±30%

2.RDC: SINGLE WIRE TEST VALUE

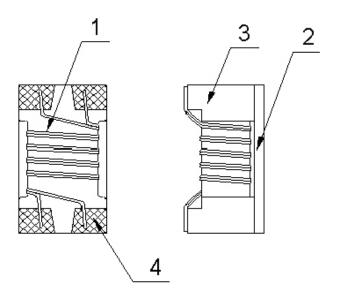
^{1.}Operating temperature range $-4~0~{\rm ^{\circ}C} \sim 1~0~5~{\rm ^{\circ}C}$ (Including self - temperature rise)

^{3.}IDC for Inductance drop 10% from its value without current.

[&]quot;-N" FOR COMPLETELY LEAD FREE TYPE(INCLUDING FERRITE BODY & SOLDER)



8 CUW11T Series 8.1 Construction:



8.2 Material List:

No	Part	Material	Supplies
1	WIRE	Grade 180	ELEKTRISOLA
2	Cover sheet	FERRITE	CHILISIN
3	CORE	FERRITE	CHILISIN
4	TERMINAL	Ag/Ni/Sn	

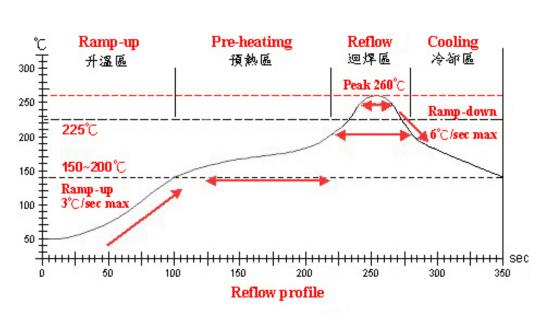


9 Common Mode Choke / RELIABILITY TEST 1-1.Environmental Performance

No	Item	Specification	Test	Method		
1-1-1	Temperature Cycle	Appearance: No Damage	One	One cycle:		
		Impedance: within±20% of	Step	Temperature (°ℂ)	Time (min)	
		initial value	1	-40±3	30	
			2	25±2	3	
			3	105±3	30	
			4	25±2	3	
			Total	: 5 cycles		
			Meas	ured After Exposure in The Roor	n Condition For 1hrs	
1-1-2	Humidity Resistance		perature: 40±2°C			
			Relative Humidity: 90 ~ 95%			
			Time: 100hrs			
			Meas	ured After Exposure In The Roor	m Condition For 1hrs	
1-1-3 High Temperature Resistance			Temp	perature: 85±3°C		
			Time	: 50Hrs		
			Meas	ured After Exposure In The Roor	m Condition For 1Hrs	
1-1-4	Low Temperature Resistance		Temp	perature: -40±3°C		
			Time	: 50Hrs		
			Meas	ured After Exposure In The Roor	n Condition For 1Hrs	
1-1-5	High Temperature Load Life	There should be no evidence	Temp	perature: 85±3°C		
		of short or open circle	Load	: Allowed DC Current		
			Time	: 500Hrs		
1-1-6	Humidity Load Life		Temp	perature: 40±2°C		
			Relat	tive Humidity: 90~95%		
			Load	: Allowed DC Current		
			Time	: 500Hrs		

No	Item	Specification	Test Method
1-2-1	Resistance To Soldering Heat	Appearance: No Damage	The device should be reflow soldered on PCB
			(peak 260°C±5°C for 10 seconds)
			2. Solder Composition: Sn/Ag3.0/Cu0.5
			3. Test time: 6 minutes
1-2-2	Solder ability	The electrodes shall be	1. Pre-Heating: 150℃,1min.
		at least 95% covered	2. Solder Composition: Sn/Ag3.0/Cu0.5
		with new solder coating	3. Solder Temperature: 245±5℃.
			4. Immersion Time: 4±1 sec.
1-2-3	Commponent Adhesion	1 Lbs. For CUW11/MCF11	The device should be reflow soldered (245±5℃ For
	(Push Test)	2 Lbs. For other	10 seconds) to a tinned copper substrate. A force guauge
			should be applied to the side of the component.
			The device must withstand a minimum force of 2 pounds
			without a failure of the termination attached to component





Lead-Free(LF) 標準溫度分析範圍

Refer to J-STD-020C

管制項目 Item.	升溫區 Ramp-up	預熱區 Pre-heatimg	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
溫度範圍 Temp.scope	R.T. ~150°C	150°C ~ 200°C	225 ℃	260±5°⊂	Peak Temp. ~ 150°C
實際時間 Time result	_	60 ~ 180 sec	20 ~ 60 sec	5 ~ 10 sec	_

NOTE:

- 1. Re-flow possible times: within 2 times
- 2. Nitrogen adopted is recommended while in re-flow



10 Packaging:

10.1 Packaging -Cover Tape

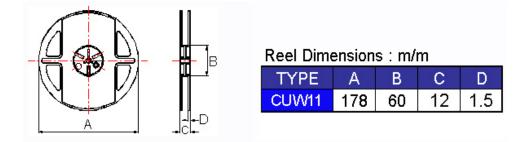
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



10.2 Packaging Quantity

TYPE	PCS/REEL
CUW11	2000

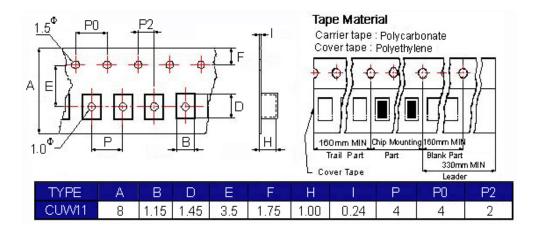
10.3 Reel Dimensions





10 Packaging:

10.4 Tape Dimensions in mm



11 Recommended Land Pattern:



12 Note:

- 1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 2. Do not knock nor drop.
- 3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose,under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)
- 5. The moisture sensitivity level (MSL) of products is classified as level 1.



13 Graph:

